

NSS055N08C



N-Channel Enhanced Shielded Gate Trench Power MOSFET

Voltage:	85 Volts	Current:	120 Ampers	Package:	TO-220C
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Features

- NH'S Advanced SGT Technology
- Low Reverse Transfer Capacitances
- Low Gate Charge For Low Switching Loss
- Excellent Qg*Rds(on) Product(FOM)

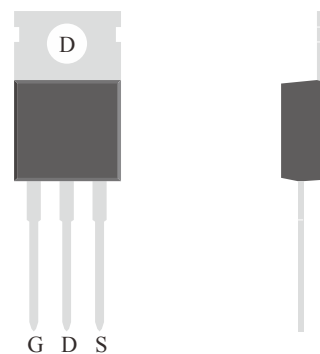
Typical Applications

- Synchronous Rectification
- High-Frequency Circuits
- The Motor Drives
- Automotive Electronics

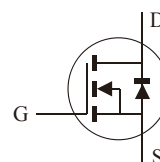
Product Summary

VDS Min.@Tj	85	V
Id Min.@Ta	120	A
RDS(ON)(TYP)@10V	4.6	mΩ

Diagram:



Polarity:



***100% UIS TESTED**

***100% ΔVDS TESTED**

Absolute Maximum Ratings (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Ratings	Unit
Drain-Source Voltage		V _{DS}	85	V
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain Current (Note 1)	Ta= 25 °C	I _D	120	A
	Ta= 100 °C		77	
Drain Current-Pulse (Note 1)	Tj< 150 °C	I _{DM}	480	A
Maximum Power Dissipation Power	Ta= 25 °C	P _D	174	W
	Ta= 100 °C		69	
Derating Factor		D _F	1.39	W/°C
Avalanche Current,Single Pulse (Note 1)	L= 0.5 mH	I _{AS}	24	A
Single Pulse Avalanche Energy (Note 1) Test Circuit & Waveform See Fig.16	L= 0.5 mH IAS= 24 A, RG= 10.0 Ω Starting Tj=25 °C, VG = 10.0 V	E _{AS}	144	mJ

Thermal Characteristics (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Typ.	Unit
Junction Temperature		T _J	-55 to 150	°C
Storage Temperature Range		T _{STD}	-55 to 150	°C
Thermal Resistance Junction To Ambient With Steady-State	Still Air Environment With Ta=25°C	R _{θJA}	62.0	°C/W
Thermal Resistance Junction-Case With Steady-State	Device Mounted On 75mm x 45mm x 2.5mm Alu. Heat.	R _{θJC}	0.72	

Notes: 1.Pulse Width Limited By Max. Junction Temperature. (See Fig. 13).

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Electrical Characteristics (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Min.	Typ.	Max.	Unit
Static Off Characteristics						
Drain-Source Breakdown Voltage	VGS=0V, ID=250uA	BV _{DSS}	85	--	--	V
Bvdss Temperature Coefficient	ID=250uA, Reference 25°C	ΔBV _{DSS} /ΔT _J	--	0.10	--	V/°C
Drain-Source Leakage Current	VDS= 85 V, VGS=0V	I _{DSS}	--	--	1	uA
Gate-Body Leakage Current	VGS= ±20 V, VDS=0V	I _{GSS}	--	--	±100	nA
Forward Transconductance	ID= 20.0 A, VDS= 5 V	g _{fs}	--	85.0	--	S
Static On Characteristics						
Gate Threshold Voltage	VGS= VDS ID=250uA	V _{GS(TH)}	2.0	3.0	4.0	V
Drain-Source On Resistance	ID= 20.0 A, VGS= 10.0 V	R _{DS(ON)}	--	4.6	5.5	mΩ
	ID= 20.0 A, VGS= 4.5 V		--	6.0	8.3	
Dynamic Characteristics						
Gate Resistance	VGS=0V, VDS=0V, Freq.=1MHz	R _g	--	3.3	--	Ω
Input Capacitance	VDS= 42.5 V	C _{iss}	--	3100.0	--	pF
Output Capacitance	VGS= 0 V	C _{oss}	--	1060.0	--	pF
Reverse Transfer Capacitance	F= 1 MHZ	C _{rss}	--	25.0	--	pF
Switching Paramters (Test Circuit & Waveform See Fig.14)						
Turn-On Delay Time	VDS= 42.5 V	t _{d(on)}	--	20.0	--	ns
Turn-On Rise Time	VGS= 10.0 V	t _r	--	39.0	--	ns
Turn-Off Delay Time	RG= 10.0 Ω	t _{d(off)}	--	45.0	--	ns
Turn-Off Rise Time		t _f	--	23.0	--	ns
Gate Charge Paramters (Test Circuit & Waveform See Fig.15)						
Total Gate Charge	VDS= 42.5 V	Q _g	--	55.0	--	nC
Gate-Source Charge	VGS= 10.0 V	Q _{gs}	--	15.0	--	nC
Gate-Drain Charge	ID= 20.0 A	Q _{gd}	--	13.0	--	nC
Drain-Source Diode Characteristics And Maximum Ratings (Test Circuit & Waveform See Fig.17)						
Max. Diode Forward Cuurent		I _S	--	--	120.0	A
Max. Pulsed Forward Cuurent		I _{SM}	--	--	480.0	A
Diode Forward Voltage	ID= 20.0 A, VGS=0V	V _{SD}	--	0.67	1.21	V
Reverse Recovery Time	IS= 20.0 A, di/dt= 100 A/us	t _{rr}	--	60.0	--	ns
Reverse Recovery Charge	VGS= 0.0 V	Q _{rr}	--	560.0	--	nC
Reverse Recovery Current		I _{RRM}	--	18.7	--	A

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Typical Characteristics Curves

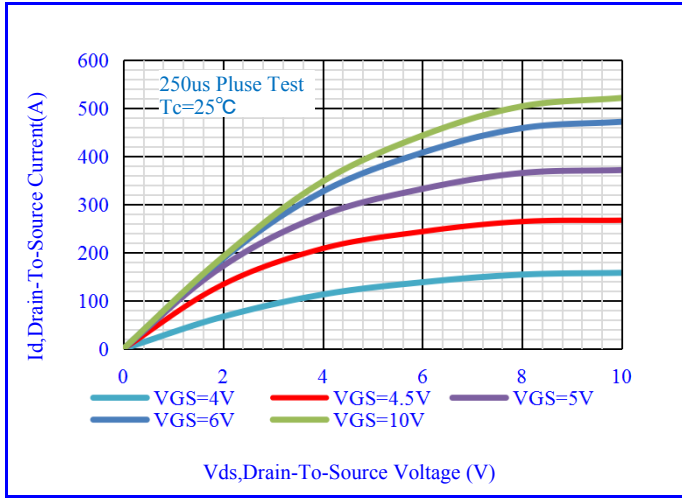


Fig.1-Output Characteristics

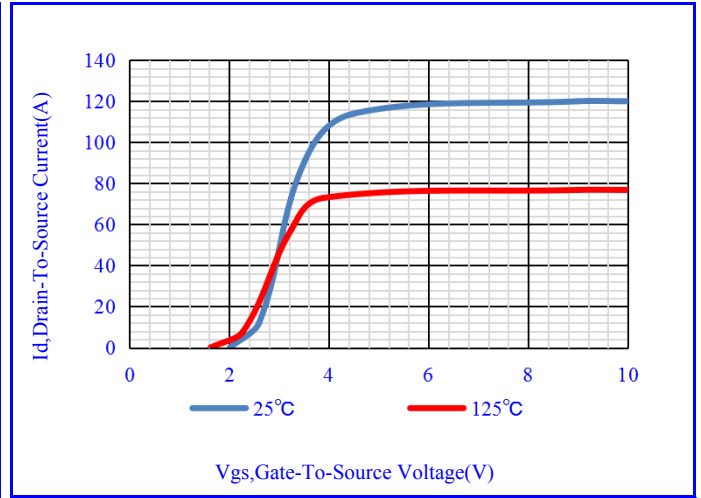


Fig.2-Transfer Characteristics

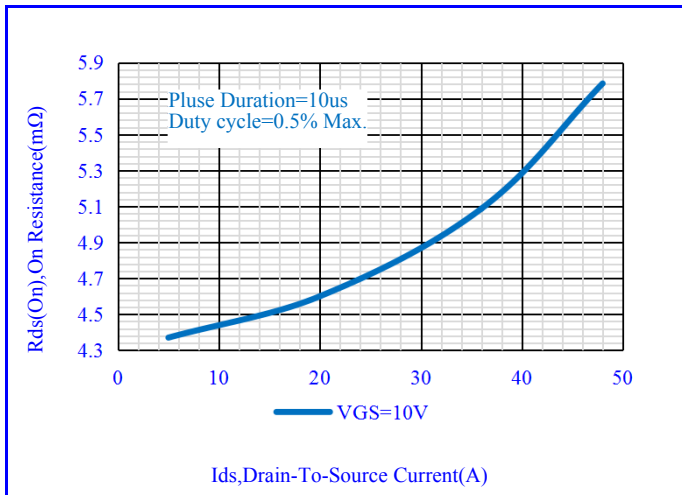


Fig.3-On Resistance Vs. Drain Current

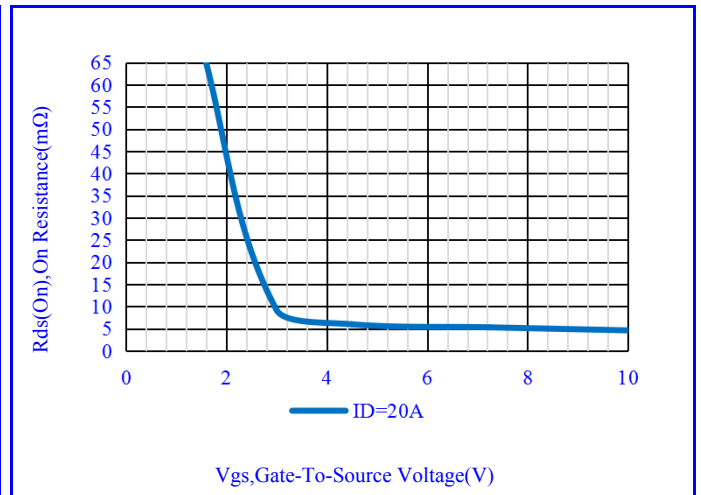


Fig.4-On Resistance Vs. Gate Source Voltage

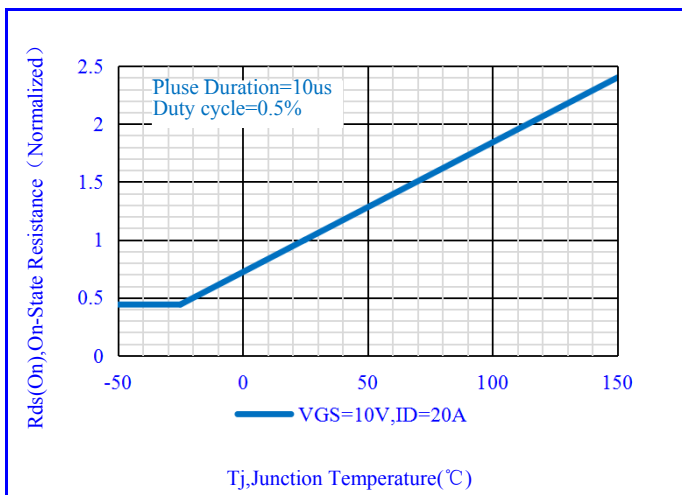


Fig.5-On Resistance Vs. Junction Temperature

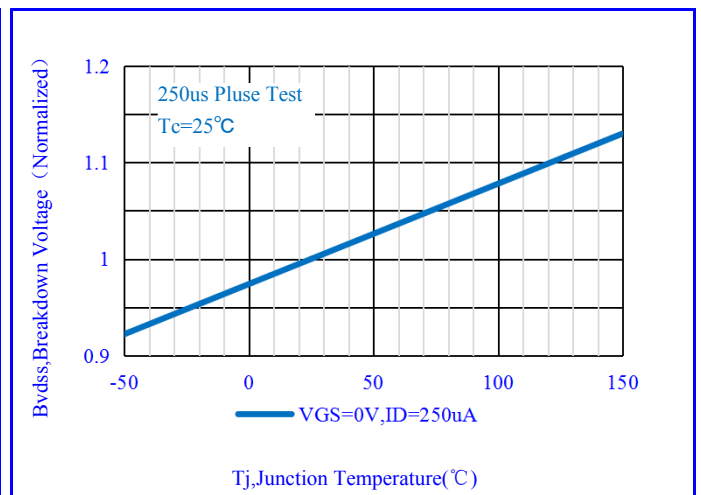


Fig.6-Breakdown Voltage Vs. Junction Temperature

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Typical Characteristics Curves

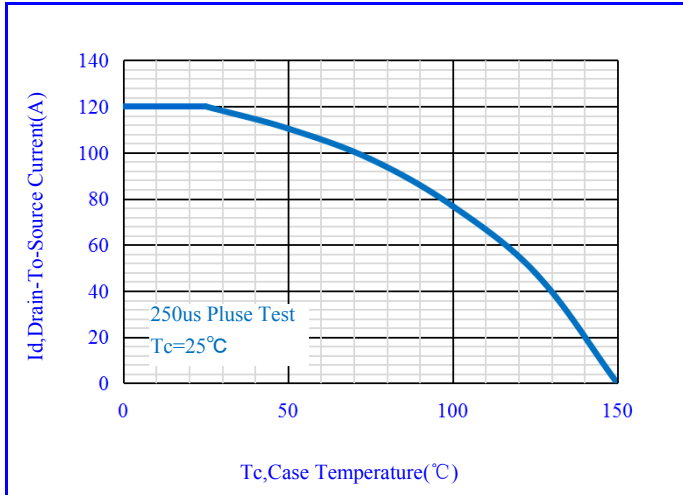


Fig.7-Maximum Continuous Drain Current Vs. Case Temperature

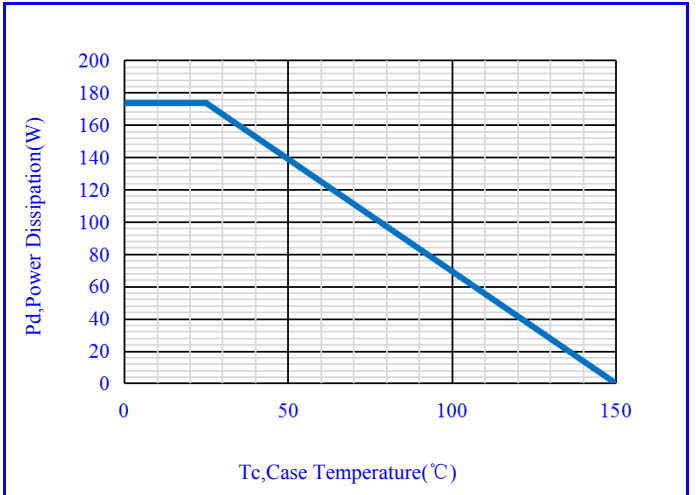


Fig.8-Maximum Power Dissipation Vs. Case Temperature

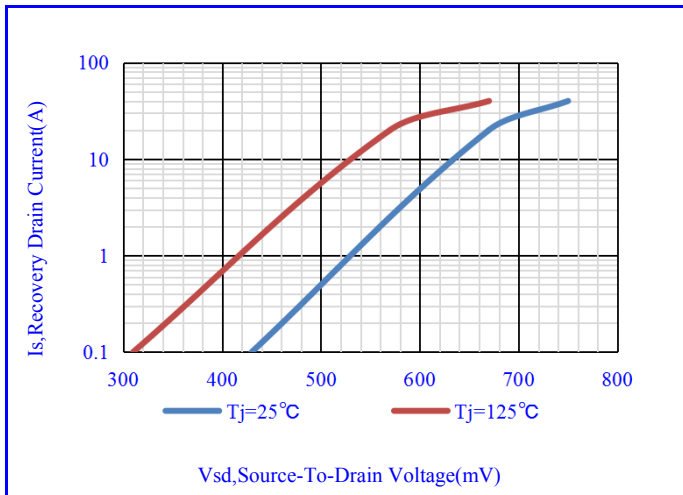


Fig.9-Source-To-Drain Diode Forward Voltage

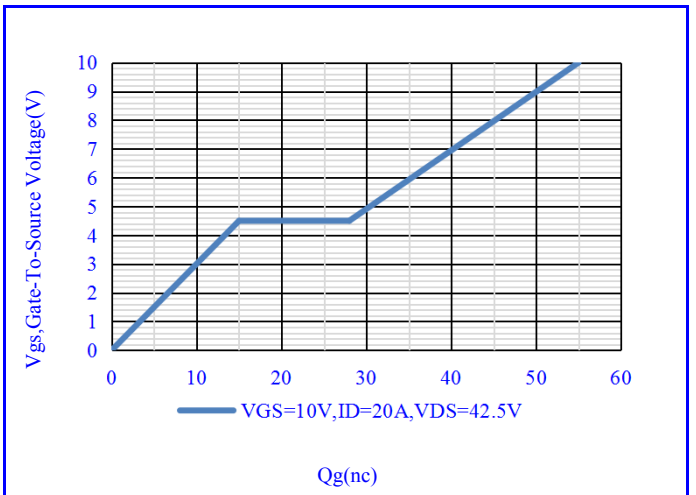


Fig.10-Gate Charge Waveform

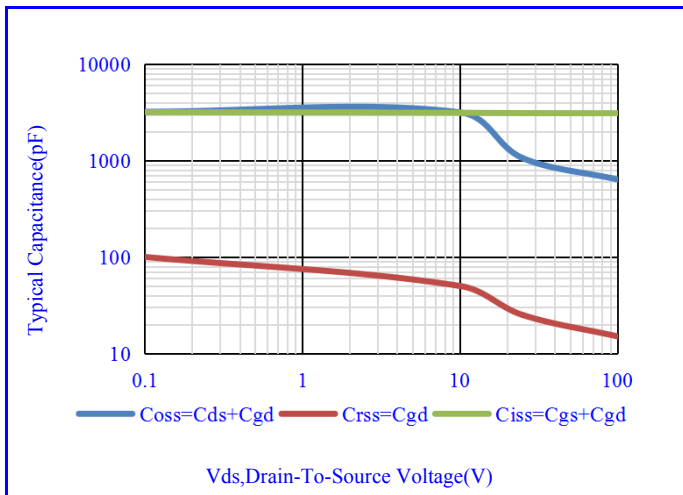


Fig.11-Typical Capacitance Vs. Drain-To-Source Voltage

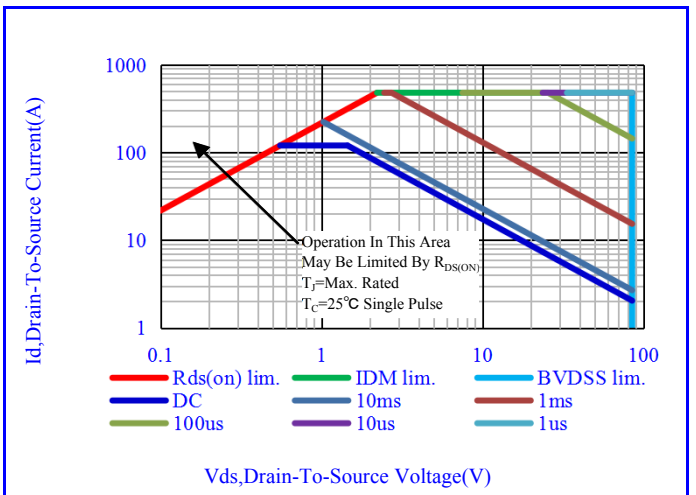


Fig.12-Maximum Safe Operating Area(SOA)

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Typical Characteristics Curves

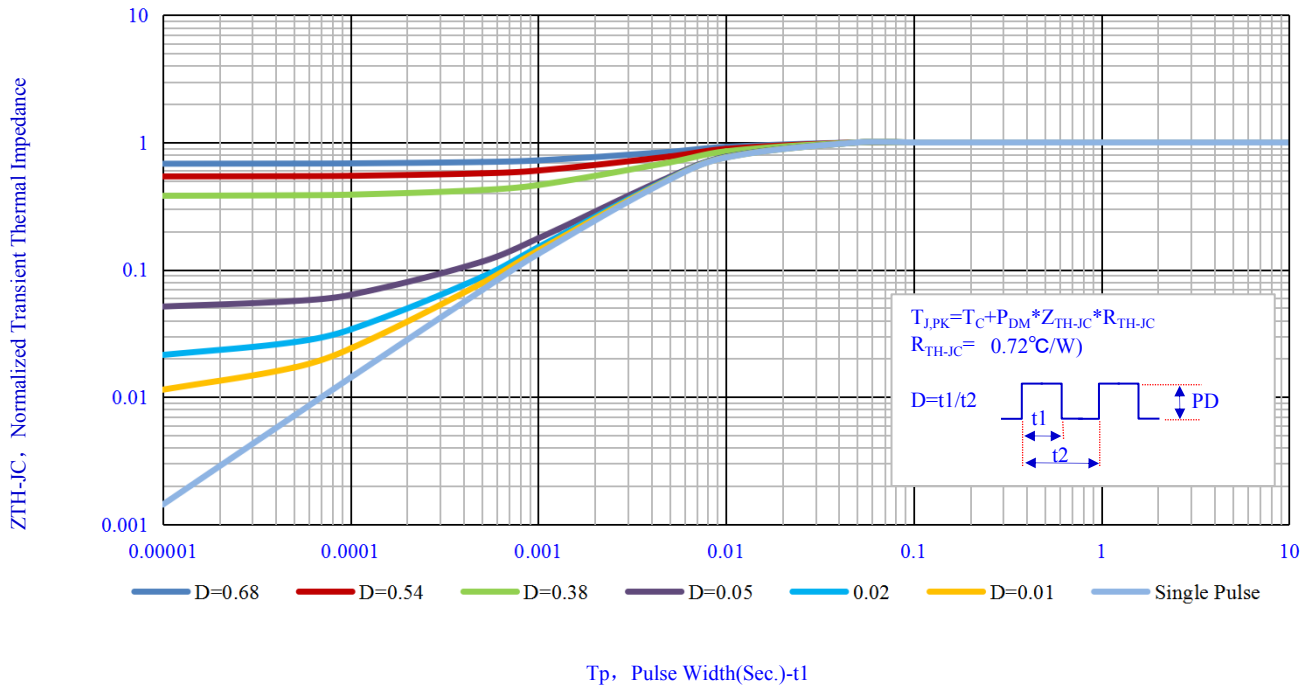


Fig.13- Normalized Maximum Transient Thermal Impedance Vs.Pulse Width

Test Circuit & Waveform

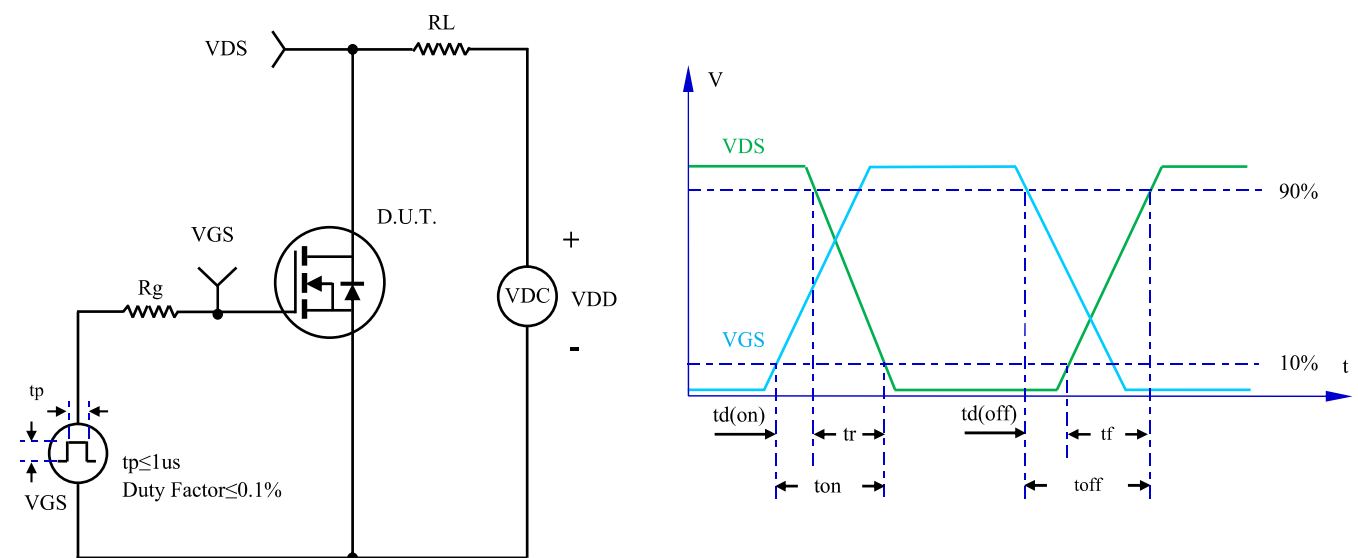


Fig.14- Resistive Switching Test Circuit & Waveform

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Test Circuit & Waveform

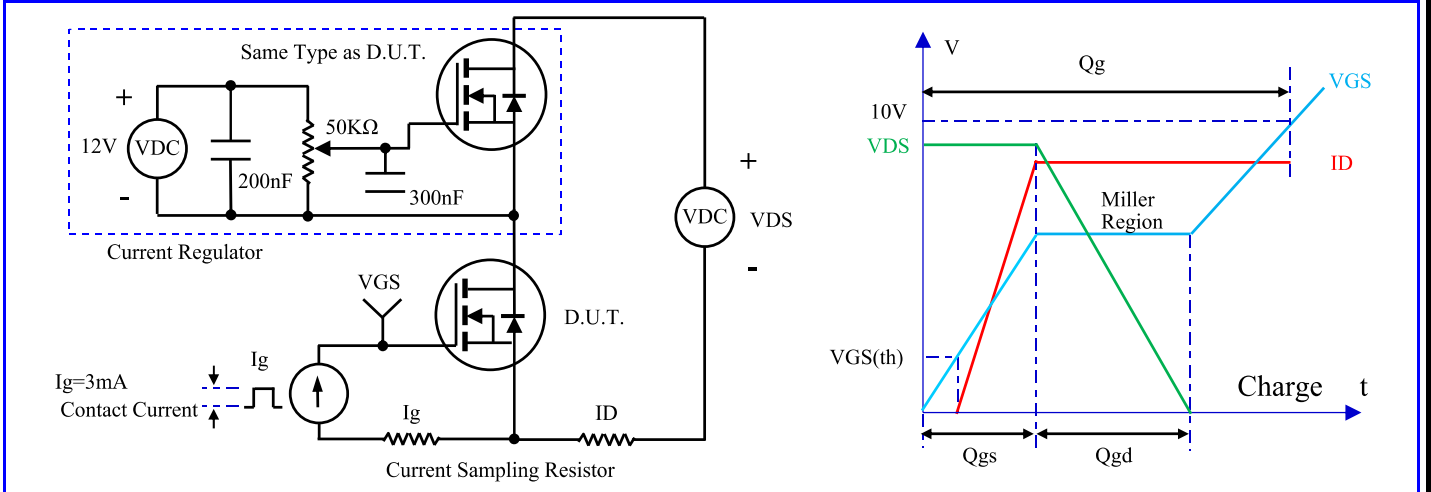


Fig.15-Gate Charge Test Circuit & Waveform

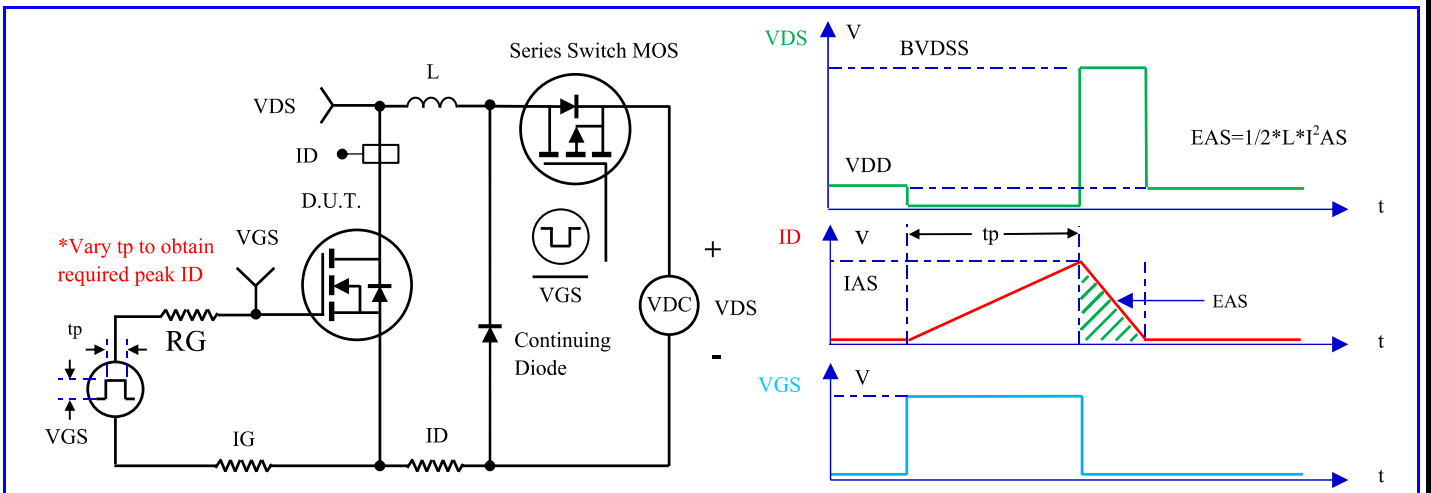


Fig.16- Unclamped Inductive Switching (UIS) Test Circuit & Waveform

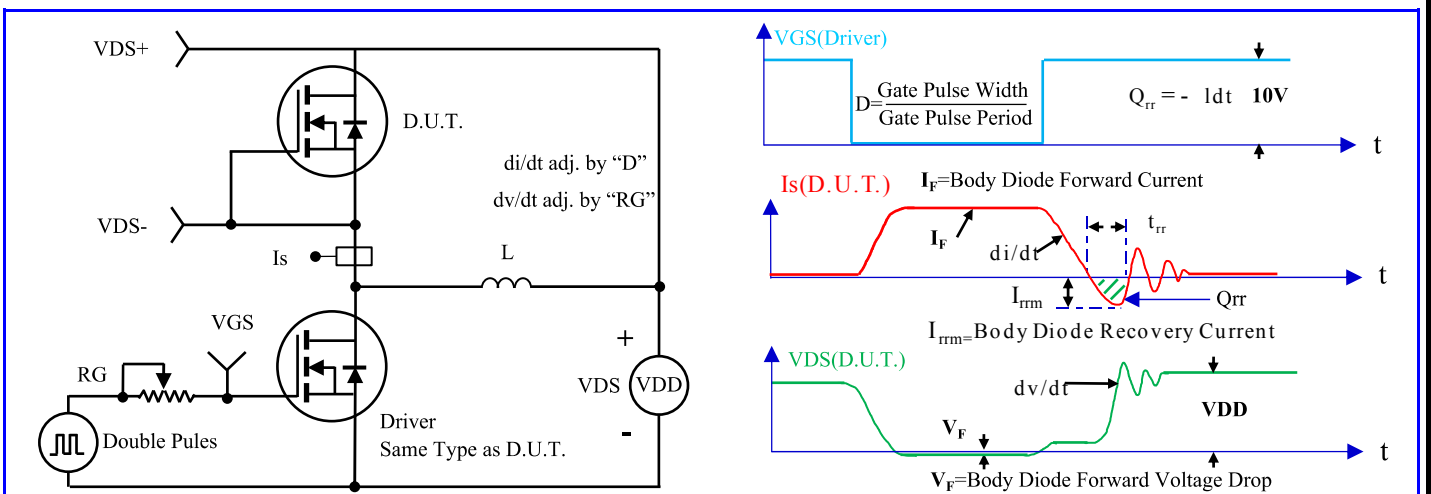


Fig.17- Diode Recovery Test Circuit & Waveform

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OUTLINE DRAWINGS		TO-220C					
		OUTLINE DIMENSIONS					
		Dim.	Millimeters			Inches	
Min.	Typ.		Max.	Min.	Typ.	Max.	
A	9.25	-	10.75	0.3642	-	0.4232	
B	4.15	-	4.95	0.1634	-	0.1949	
C	1.10	-	1.65	0.0433	-	0.0650	
D	0.25	-	0.65	0.0098	-	0.0256	
E	14.50	-	16.70	0.5709	-	0.6575	
F	8.40	-	9.95	0.3307	-	0.3917	
L	12.15	-	14.30	0.4783	-	0.5630	
H	3.00	-	3.80	0.1181	-	0.1496	
J	1.05	-	1.60	0.0413	-	0.0630	
K	0.65	-	0.95	0.0256	-	0.0374	
M	2.10	-	2.90	0.0827	-	0.1142	
O	3.20	-	4.10	0.1260	-	0.1614	
P	2.45	-	3.10	0.0965	-	0.1220	

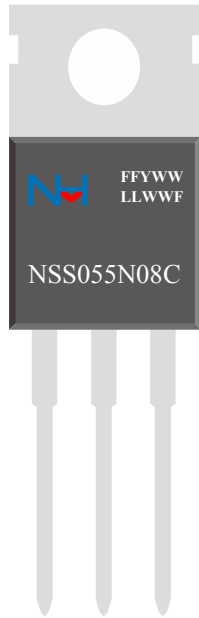
RECOMMENDED LAYOUT DRAWINGS		TO-220C					
		OUTLINE DIMENSIONS					
		Dim.	Millimeters			Inches	
Min.	Typ.		Max.	Min.	Typ.	Max.	
A	-	1.60	-	-	0.0630	-	
B	-	1.60	-	-	0.0630	-	
C	-	2.54	-	-	0.1000	-	
D	-	1.00	-	-	0.0394	-	

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MARKING INFORMATION



MARKING INSTRUCTIONS

NH=Niuhan Trademark
 FF=Product Line Code,According To Actual Changes
 YWW=Date Code,According To Actual Changes
 LLWWF=Internal Code,According To Actual Changes
 NSS055N08C=Model

PACKING INFORMATION

Package Type	Package Code	Product Weight Approx(g/Pcs)	Package Method	Quantity (Pcs/Min. Pack.)	Quantity (Pcs/Inner Box)	Quantity (Pcs/Carton)
TO-220C	P1	2.057	Tube	50	1000	5000

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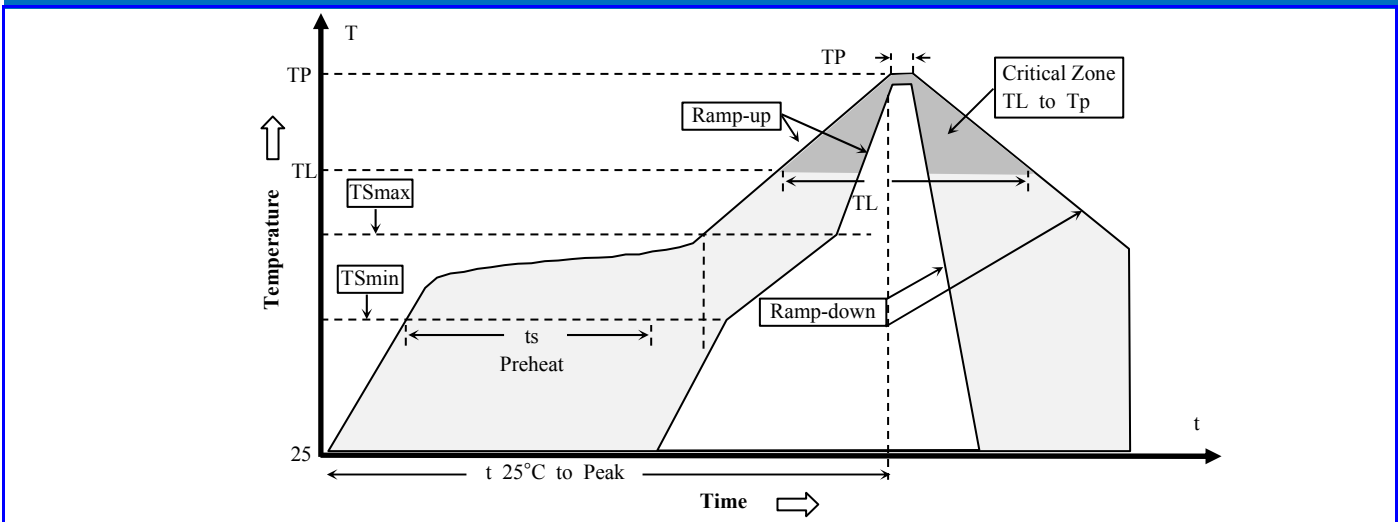


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Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat -Temperature Min(T _{S min}) -Temperature Max(T _{S max}) -Time(t _{s min} to t _{s max})	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: -Temperature (T _L) - Time (t _L)	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature(T _p)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(t _p)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

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